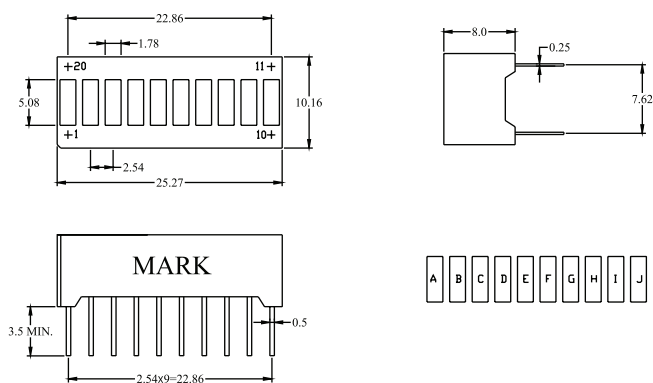


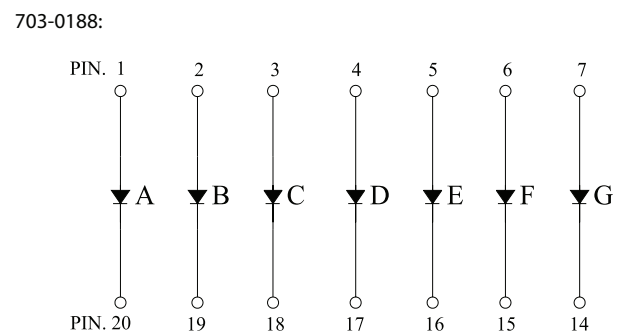
10 Segment Light Bar



Package Dimensions:



Internal Circuit Diagram:



All dimensions are in mm
 Tolerance: $\pm 0.25\text{mm}$
 The slope angle of any PIN may be $\pm 5^\circ$ max

Absolute Maximum Ratings at $T_a=25^\circ\text{C}$

Parameter	Symbol	Rating	Unit
Power Dissipation - Pre Segment	P_D	78	mW
Pulse Current (1/10 Duty Cycle, 0.1ms Pulse Width) - Per Chip	I_{FP}	100	mA
Forward Current - Per Chip	I_F	30	mA
Reverse (Leakage) Current - Per Chip	I_r	100	μA
Reverse Voltage - Per Chip	V_R	5	V
Operating Temperature Range	Topr.	-25 to +85	$^\circ\text{C}$
Storage Temperature Range	Tstg.	-40 to +100	$^\circ\text{C}$
Soldering Temperature	Tsol.	Dip Soldering: 260°C for 5sec. Hand Soldering: 350°C for 3 sec.	



10 Segment Light Bar



Electrical & Optical Characteristics:

Parameter	Symbol	Condition	Min.	Typ.	Max.	Unit
Luminous Intensity - Per Segment	I_v	$I_f=10\text{mA} / \text{Dot}$	1.7	3.4		mcd
Forward Voltage	V_f	$I_f=20\text{mA} / \text{Dot}$		2.1	2.6	V
Peak Wavelength	λ_p	$I_f=20\text{mA} / \text{Dot}$		567		nm
Dominant Wavelength	λ_d	$I_f=20\text{mA} / \text{Dot}$		572		nm
Reverse Current - Per Chip (Leakage Current - Per Chip)	I_r	$V_r=5\text{V}$			100	μA
Spectrum Line Halfwidth	$\Delta\lambda$	$I_f=20\text{mA} / \text{Dot}$		30		deg
Response Time	T			250		nm

Note: Customer's special requirements are also welcome.

Typical Electrical & Optical Characteristics Curves:

(25°C Ambient temperature unless otherwise noted)

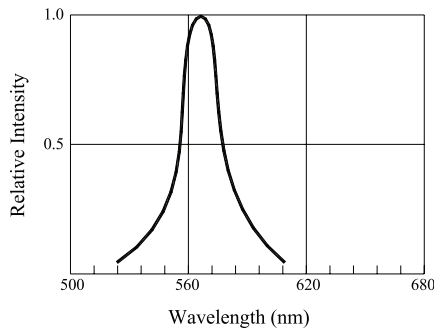


Fig.1 RELATIVE INTENSITY VS. WAVELENGTH

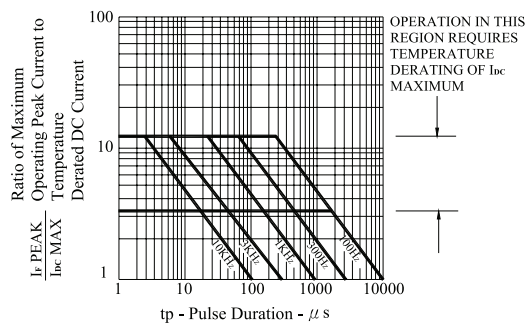


Fig.2 MAXIMUM TOLERABLE PEAK CURRENT VS. PULSE DURATION

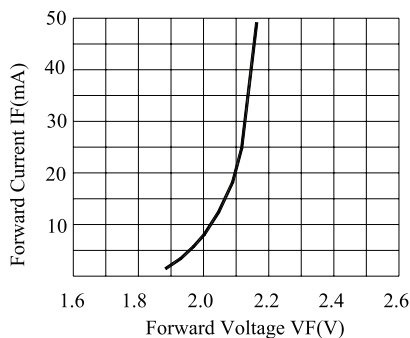


Fig.3 FORWARD CURRENT VS. FORWARD VOLTAGE PER CHIP

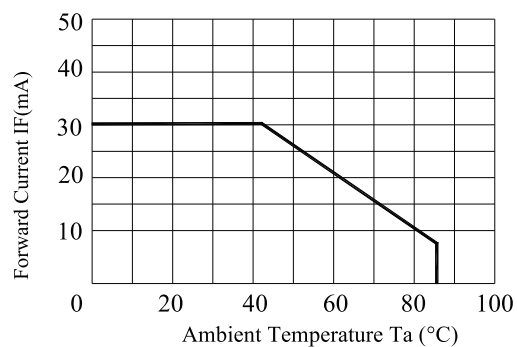


Fig.4 FORWARD CURRENT VS. DERATING CURVE

